GCS InGaAs Monitor PIN PD

P/N: Do064_200um_P2



DATASHEET



Introduction

This product is a front side illuminated InGaAs monitor PIN photodiode chip that features a planar structure with anode on front side and cathode on backside. This product has a large 200 μ m detection window, and is designed primary to be integrated with a FP or DFB laser in a hermetic TO package, for monitoring the optical power output emitted from the back facet of the edge emitting laser, with excellent responsivity in the wavelength region from 980nm to 1620nm.

Applications

Back facet laser power

monitoring

- Planar structure on n+ InP substrate with top anode contact
- 200µm optical detection window optimized for monitoring FP or DFB lasers
- Low operating bias voltage
- -40C to 85C operation range
- Deliverable in GCS Known Good Die[™] with 100% testing and inspection
- RoHS compliant

Key Features

	Conditions	Min.	Typical	Max.	Unit	Notes
	1310nm	0.8	0.9	-	A/W	
Responsivity	1550nm	0.9	0.95	-	A/W	
Capacitance	-5 V	-	3.3	4	pF	
Forward Voltage	1mA	-	0.54	0.6	V	
Breakdown	1μA	20	-	-	V	
Dark current	-5V	-	0.3	1	nA	
Bandwidth		-	0.5	-	GHz	

SPECIFICATIONS (T=25C°)

ABSOLUTE MAXIMUM RATING

Parameter	Rating
ESD Rating	300V
Reverse Voltage	-20V
Reverse Current	-10mA
Forward Current	10mA
Optical Power Input	10mW
Operating Temperature	-40C to 85C
Storage Temperature	-40C to 125C
Soldering Temperature	320C / 5 sec

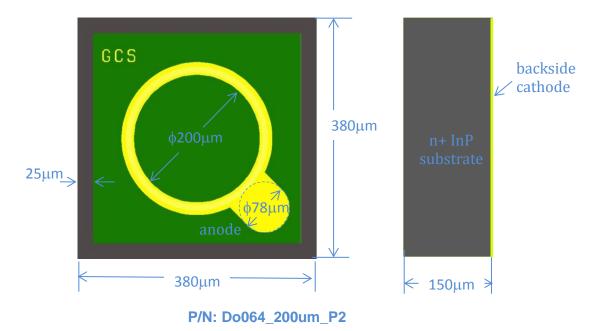
Global Communication Semiconductors, LLC 23155 Kashiwa Court, Torrance, CA 90505 Tel: (310) 530-7274 Fax: (310) 517-8200 e-mail: info@gcsincorp.com www.gcsincorp.com

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Made in USA

DIMENSIONS (S&B dicing)							
	Conditions	Min.	Typical	Max.	Unit	Notes	
Detection Window			200		μm		
Bonding pad diameter			78		μm	for p-pad	
Metal height of bond pads			1.6	-	μm	Au metal	
Die height		140	150	160	μm		
Die width		370	380	390	μm		
Die length		370	380	390	μm		



Attention: InP is a brittle material and the device is electrostatic sensitive; observe precaution in handling.

About GCS:

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GCS has a long history manufacturing and shipping both GaAs and InGaAs based photo diodes since 2000. Our state of art manufacturing facility is located in Torrance, California, and has about 10,000 square feet of fab space with a capability of about 1200 4-inch wafers per month and expandable to 2000 wafers per month. GCS as a world-class semiconductor device manufacturer has been delivering a total of over 30 million photo diodes with various date rates and applications used for optical communications, which have been deployed in field by top tier optical transceiver companies worldwide.

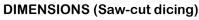
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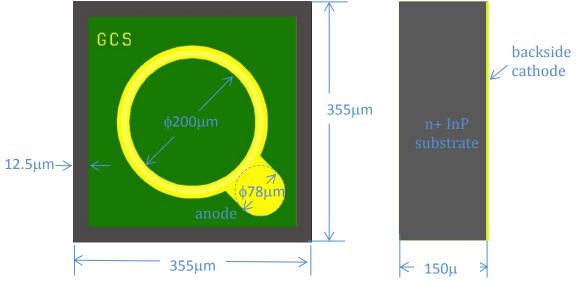
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Made in USA

DIMENSIONS (Saw-cut dicing)							
	Conditions	Min.	Typical	Max.	Unit	Notes	
Detection Window			200		μm		
Bonding pad diameter			78		μm	for p-pad	
Metal height of bond pads			1.6	-	μm	Au metal	
Die height		140	150	160	μm		
Die width		340	355	370	μm		
Die length		340	355	370	μm		





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